

**IN-SITU MELT AND REFLOW PROCESS FOR FORMING FLIP-CHIP
INTERCONNECTIONS AND SYSTEM THEREOF**

ABSTRACT

A method for an electronic device packaging comprising abutting a semiconductor device to a carrier substrate. The semiconductor device comprises a plurality of bump structures on its surface, said bumps comprising a soldier portion. The carrier substrate comprises a plurality of contact pads on its surface. The semiconductor device is heated to a first temperature, higher than the melting temperature of the soldier portions of the bumps, and the carrier substrate is heated to a second temperature. The plurality of bumps on semiconductor device is thereafter aligned with the plurality of contact pads on the carrier support. The semiconductor device and the carrier support are then brought in contact for subsequent abutting of the bumps to corresponding contact pads.

FIG. 1